

AP01L60AT-VB Datasheet

Power MOSFET

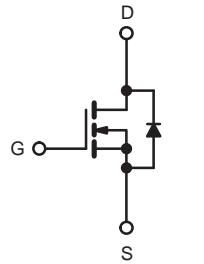
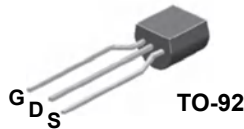
PRODUCT SUMMARY	
V _{DS} (V)	650
R _{DS(on)} (Ω)	V _{GS} = 10 V 8
Q _g (Max.) (nC)	18
Q _{gs} (nC)	3.0
Q _{gd} (nC)	8.9
Configuration	Single

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Available in Tape and Reel
- Fast Switching
- Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC



Available
RoHS*
COMPLIANT
HALOGEN
FREE
Available



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V _{DS}	650	V	
Gate-Source Voltage	V _{GS}	± 20		
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	1.0	A
		T _C = 100 °C	0.7	
Pulsed Drain Current ^a	I _{DM}	2.0	W/°C	
Linear Derating Factor		0.33		
Linear Derating Factor (PCB Mount) ^e		0.020		
Single Pulse Avalanche Energy ^b	E _{AS}	74	mJ	
Repetitive Avalanche Current ^a	I _{AR}	2.0	A	
Repetitive Avalanche Energy ^a	E _{AR}	4.2	mJ	
Maximum Power Dissipation	T _C = 25 °C		42	W
		T _A = 25 °C	2.5	
Maximum Power Dissipation (PCB Mount) ^e				
Peak Diode Recovery dV/dt ^c	dV/dt	3.0	V/ns	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s	260 ^d		

Notes

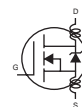

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- V_{DD} = 50 V, starting T_J = 25 °C, L = 37 mH, R_g = 25 Ω, I_{AS} = 2.0 A (see fig. 12).
- I_{SD} ≤ 2.0 A, di/dt ≤ 40 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R_{thJA}	-	-	110	°C/W	
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	-	50		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	-	3.0		

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNIT	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		650	-	- V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$		-	0.88	- $V/^\circ\text{C}$	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0 V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100\text{ nA}$	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$		-	-	100 μA	
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	500 μA	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 1.0\text{ A}^b$	--	8	- Ω	
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 1.0\text{ A}$		1.4	-	- S	
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = -25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$		-	350	-	
Output Capacitance	C_{oss}			-	48	-	pF
Reverse Transfer Capacitance	C_{rss}			-	8.6	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 1.0\text{ A}, V_{DS} = 360\text{ V}, \text{ see fig. 6 and 13}^b$	-	-	18	
Gate-Source Charge	Q_{gs}			-	-	3.0	nC
Gate-Drain Charge	Q_{gd}			-	-	8.9	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300\text{ V}, I_D = 1.0\text{ A}, R_g = 18\text{ }\Omega, R_D = 135\text{ }\Omega, \text{ see fig. 10}^b$		-	10	-	
Rise Time	t_r			-	23	-	ns
Turn-Off Delay Time	$t_{d(off)}$			-	30	-	
Fall Time	t_f			-	25	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	
Internal Source Inductance	L_S			-	7.5	-	nH
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	2.0	
Pulsed Diode Forward Current ^a	I_{SM}			-	-	8.0	A
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 2.0\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.6 V	
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 2.0\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	290	580 ns	
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.67	1.3 μC	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\text{ }\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

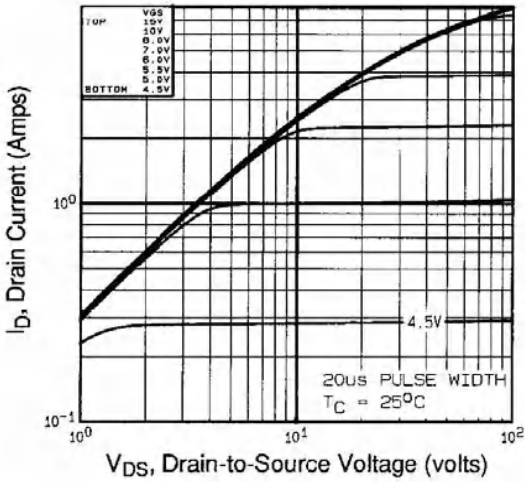


Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$

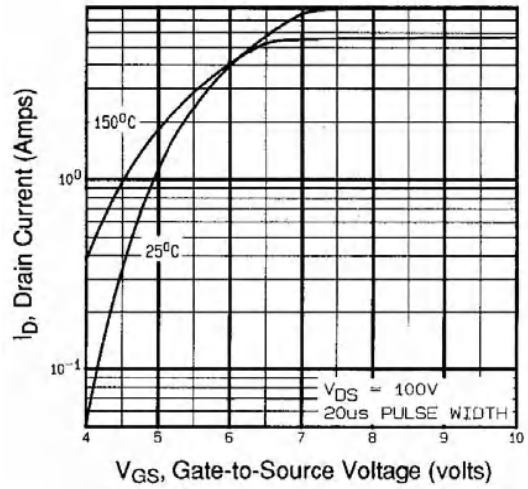


Fig. 3 - Typical Transfer Characteristics

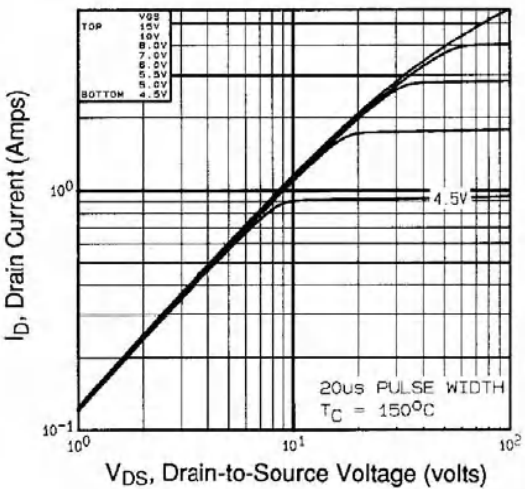


Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ }^\circ\text{C}$

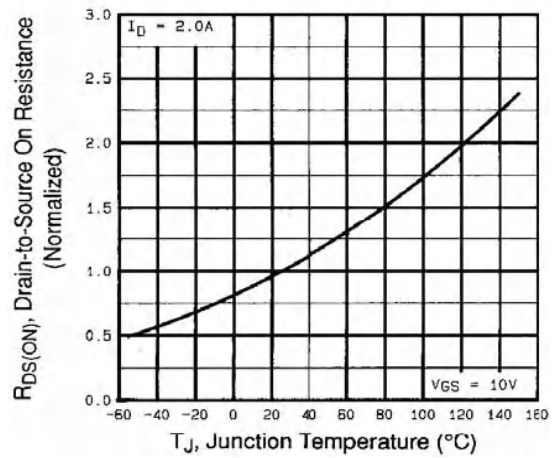


Fig. 4 - Normalized On-Resistance vs. Temperature

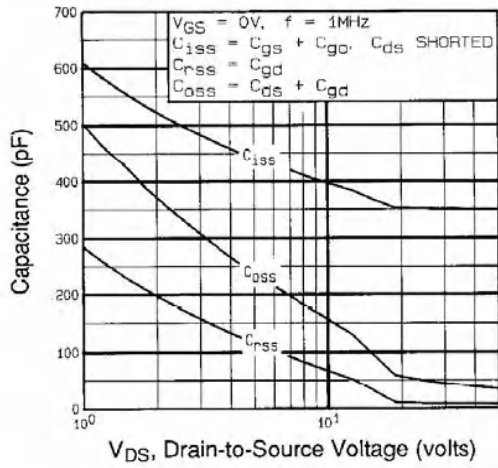


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

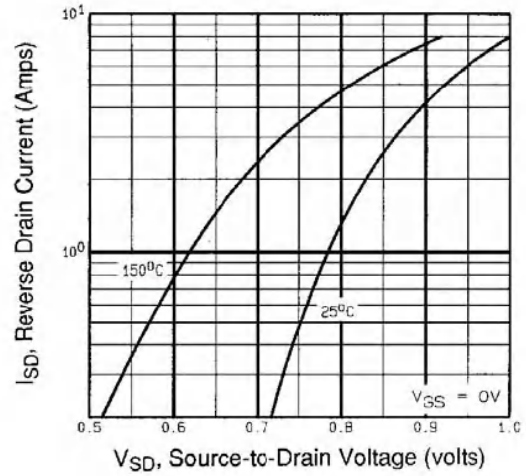


Fig. 7 - Typical Source-Drain Diode Forward Voltage

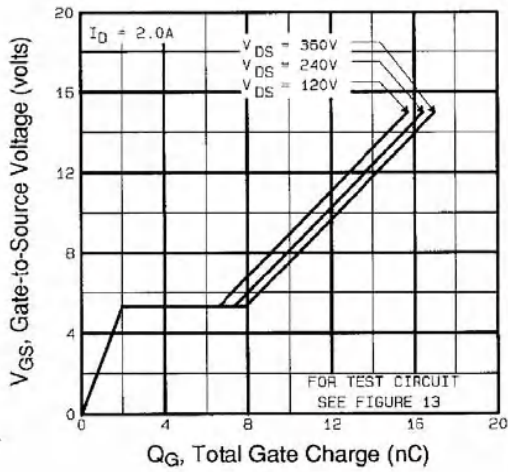


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

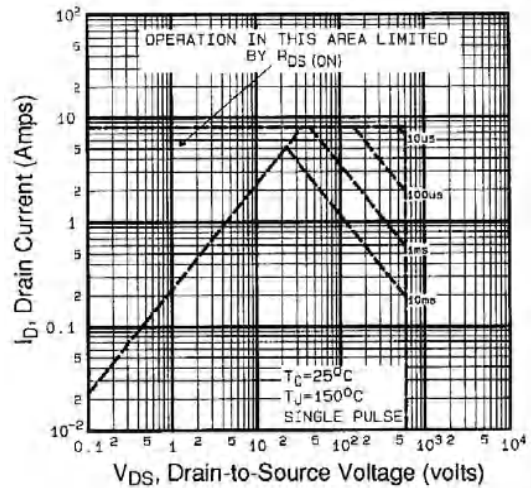


Fig. 8 - Maximum Safe Operating Area

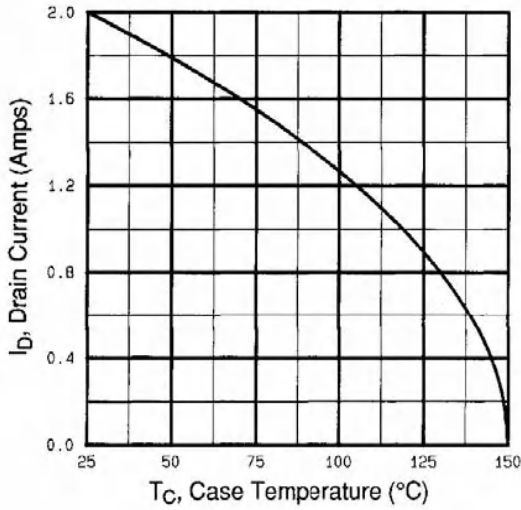


Fig. 9 - Maximum Drain Current vs. Case Temperature

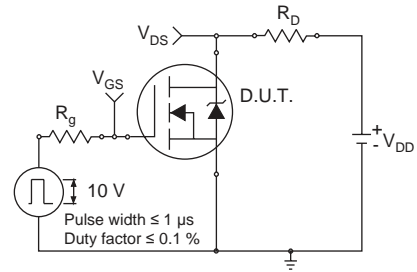


Fig. 10a - Switching Time Test Circuit

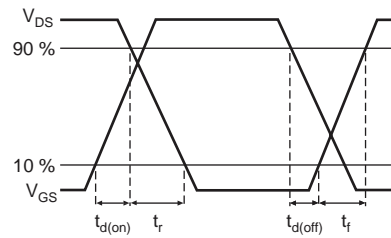


Fig. 10b - Switching Time Waveforms

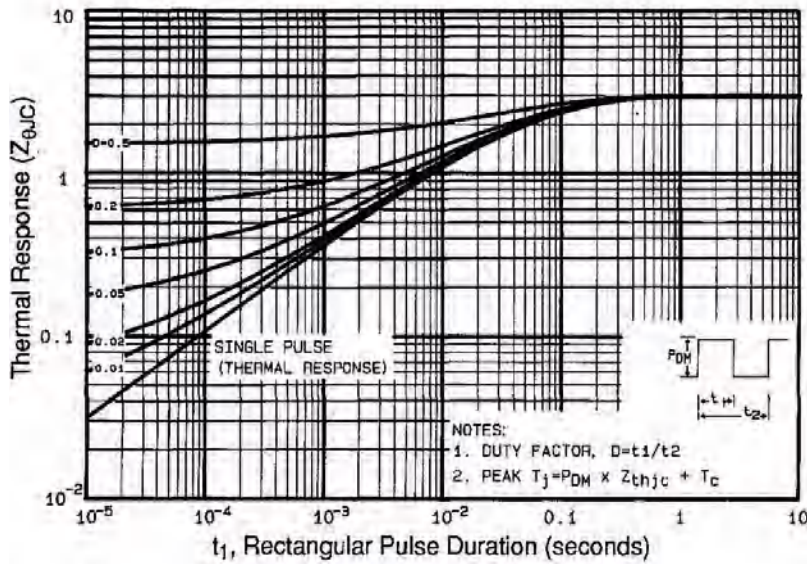


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

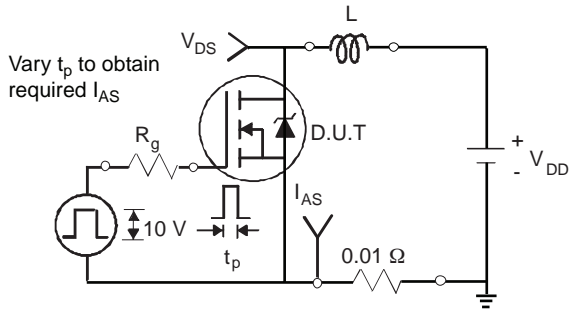


Fig. 12a - Unclamped Inductive Test Circuit

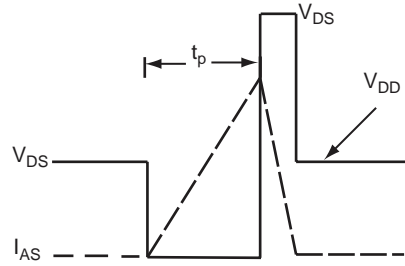


Fig. 12b - Unclamped Inductive Waveforms

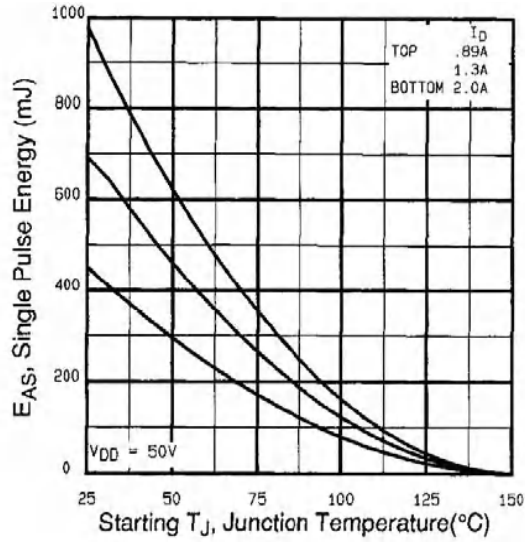


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

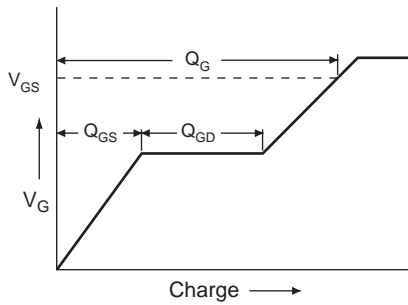


Fig. 13a - Basic Gate Charge Waveform

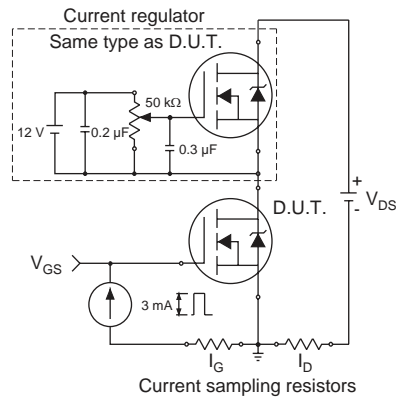
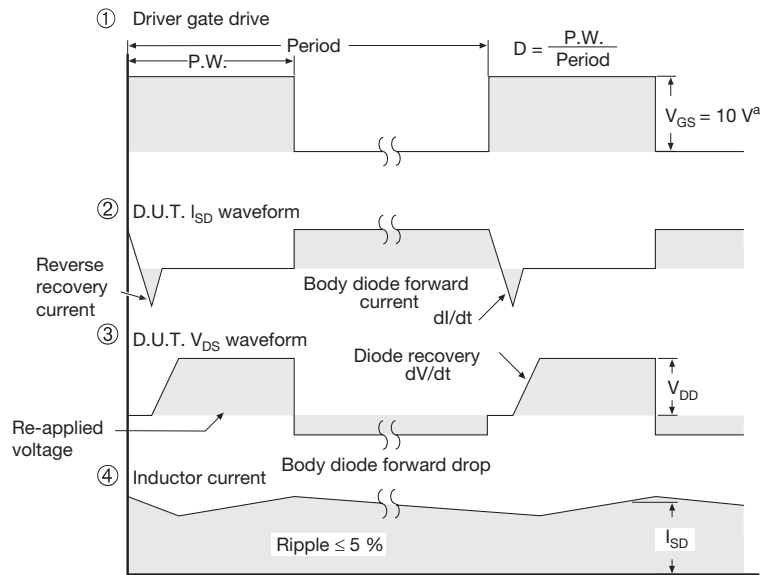
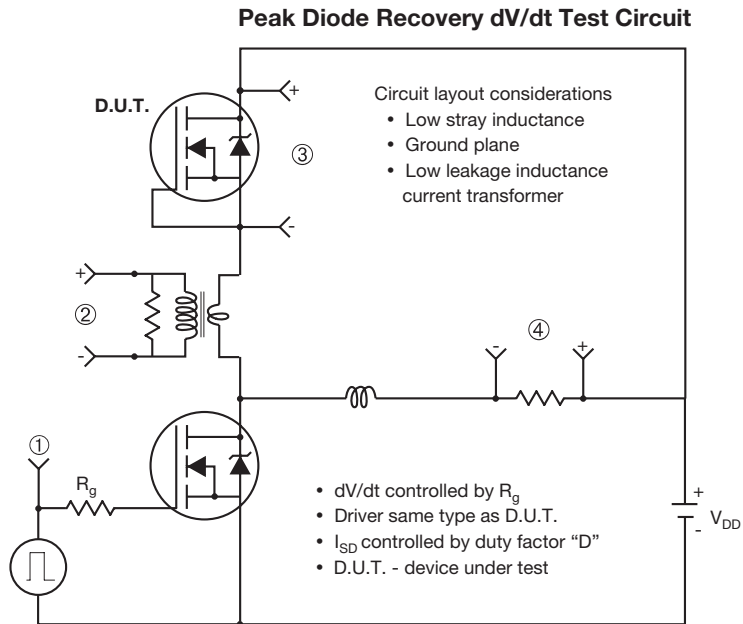


Fig. 13b - Gate Charge Test Circuit

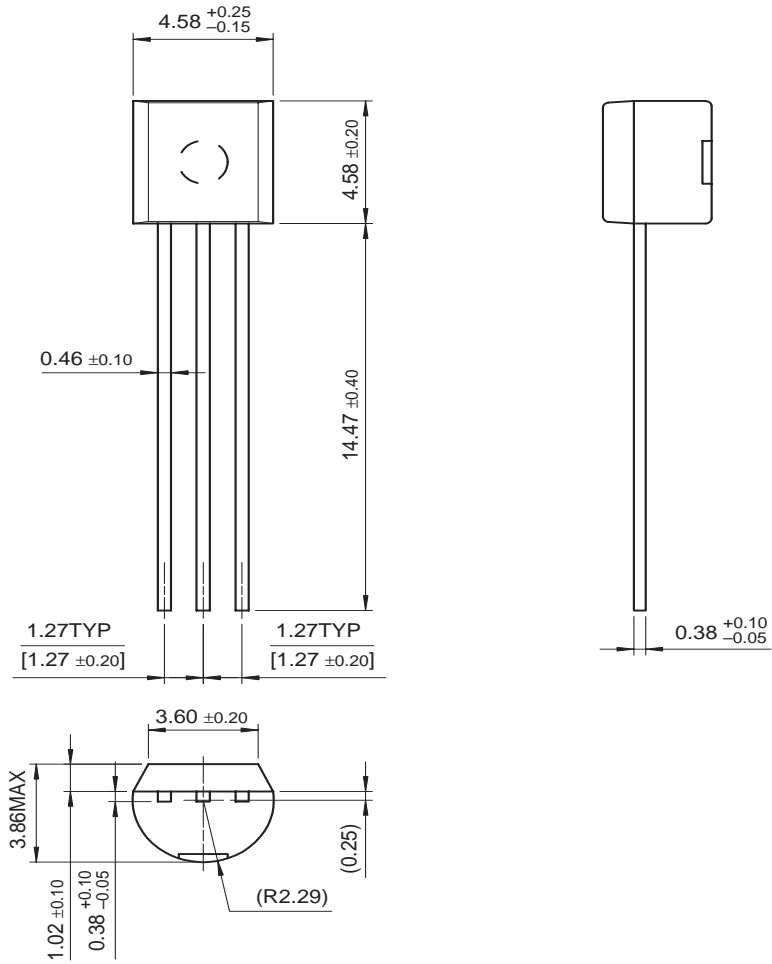


Note
 a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

Mechanical Dimensions

TO-92



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